



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16961Generic Copy

Issue Date: 08-Jan-2013**TITLE:** Change from 4" wafer to 6" wafer for TCA0372 and TCA0372B Device family**PROPOSED FIRST SHIP DATE:** 0-Jul-2012**AFFECTED CHANGE CATEGORY(S):** Process Enhancement**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or <Shannon.Riggs@onsemi.com>**SAMPLES:** Contact your local ON Semiconductor Sales Office or <Shannon.Riggs@onsemi.com>**ADDITIONAL RELIABILITY DATA:** AvailableContact your local ON Semiconductor Sales Office or <Shannon.Riggs@onsemi.com>**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.**DESCRIPTION AND PURPOSE:**

This is the Final PCN announcing ON Semiconductor's transfer of the TCA0372 and TCA0372B Device families from the 4" wafer process to the 6" wafer process. This change is to bring the design up to compliance with the current standards for the process technology. The device designs were revised to match the latest design rules for the wafer process.

As of the effective date, material assembled after W27, 2012 may be assembled with the 6" material. Please note this change has already occurred.


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RELIABILITY DATA SUMMARY:

Qualification vehicle: NCP1536

Test	Standard	Description and Read Points	Test Conditions	(rej/ss)
PC	JESD22 A113 J-STD-020	Preconditioning: (Test @Rm) Moist. Precond.	Peak reflow temp=260degC	0/693
HAST	JESD22 A110	High Accel Stress Test: (Test @R) 130°C/85% RH for 96hrs		0/231
AC	JESD22 A102	Autoclave: (Test @R) 121°C/100% RH/ 15 PSIG for 96hrs		0/231
TC	JESD22 A104	Temp Cycle: (Test @R) -65°C to+150°C; for 500 cycles		0/231
HTSL	JESD22 A103	High Temp Storage Life (Test @R) TA= 150°C for 1000 hrs.		0/45
Test Group B- Accelerated LifeTime Simulation Tests				
HTOL	JESD22 A108	High Temp Op Life: (Test @ R) TA=125°C for 1008 hrs.	Vcc=Max	0/231
ELFR	AEC-Q100-008	Early Life Fail Rate: (Test @R) TA= 125°C for 48hrs of TA= 150°C for 24hrs.	Used existing data and data from present HTOL	0/2400

ELECTRICAL CHARACTERISTIC SUMMARY:

Electrical characterization has been completed with changes noted in Product Bulletin #16895. ON Semiconductor recommends samples are obtained for application specific review.

List of affected General Parts:

TCA0372DWR2G
TCA0372BDWR2G